32,768-word × 8-bit High Speed CMOS Static RAM

# **HITACHI**

ADE-203-135D (Z) Rev. 4.0 Nov. 29, 1995

#### **Description**

The Hitachi HM62256B is a CMOS static RAM organized 32-kword  $\times$  8-bit. It realizes higher performance and low power consumption by employing 0.8  $\mu$ m Hi-CMOS process technology. The device, packaged in 8  $\times$  14 mm TSOP, 8  $\times$  13.4 mm TSOP with thickness of 1.2 mm, 450-mil SOP (foot print pitch width), 600-mil plastic DIP, or 300-mil plastic DIP, is available for high density mounting. It offers low power standby power dissipation; therefore, it is suitable for battery back-up systems.

#### **Features**

High speed

Fast access time: 45/55/70/85 ns (max)

Low power

Standby:  $1.0 \,\mu\text{W}$  (typ)

Operation: 25 mW (typ) (f = 1 MHz)

- Single 5 V supply
- Completely static memory

No clock or timing strobe required

- · Equal access and cycle times
- Common data input and output
  - Three state output
- Directly TTL compatible

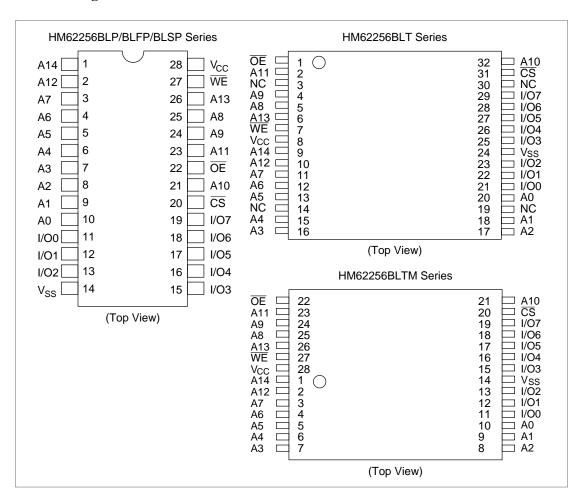
  All inputs and outputs
  - All inputs and outputs
- · Capability of battery back up operation

# **Ordering Information**

Type No.	Access Time	Package
HM62256BLP-7	70 ns	600-mil 28-pin plastic DIP (DP-28)
HM62256BLP-7SL	70 ns	
HM62256BLSP-7	70 ns	300-mil 28-pin plastic DIP (DP-28NA)
HM62256BLSP-7SL	70 ns	
HM62256BLFP-7T	70 ns	450-mil 28-pin plastic SOP (FP-28DA)
HM62256BLFP-4SLT <sup>*1</sup> HM62256BLFP-5SLT HM62256BLFP-7SLT	45 ns 55 ns 70 ns	
HM62256BLFP-7ULT	70 ns	_
HM62256BLT-8	85 ns	8 mm × 14 mm 32-pin TSOP (TFP-32DA)
HM62256BLT-7SL	70 ns	_
HM62256BLTM-8	85 ns	8 mm × 13.4 mm 28-pin TSOP (TFP-28DA)
HM62256BLTM-4SL <sup>-1</sup> HM62256BLTM-5SL HM62256BLTM-7SL	45 ns 55 ns 70 ns	_
HM62256BLTM-7UL	70 ns	

Note: 1. Under development

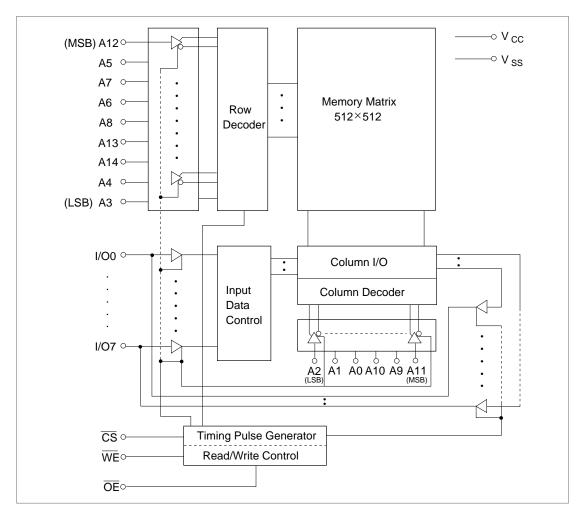
#### **Pin Arrangement**



### **Pin Description**

Symbol	Function
A0 – A14	Address
I/O0 – I/O7	Input/output
CS	Chip select
WE	Write enable
ŌĒ	Output enable
NC	No connection
V <sub>cc</sub>	Power supply
V <sub>SS</sub>	Ground

# **Block Diagram**



# **Function Table**

WE	CS	ŌĒ	Mode	V <sub>cc</sub> Current	I/O Pin	Ref. Cycle
Χ	Н	Х	Not selected	$I_{SB}, I_{SB1}$	High-Z	_
Н	L	Н	Output disable	I <sub>cc</sub>	High-Z	_
Н	L	L	Read	I <sub>cc</sub>	Dout	Read cycle (1)–(3)
L	L	Н	Write	I <sub>cc</sub>	Din	Write cycle (1)
L	L	L	Write	I <sub>cc</sub>	Din	Write cycle (2)

Note: X: H or L

# **Absolute Maximum Ratings**

Parameter	Symbol	Value	Unit
Power supply voltage <sup>*1</sup>	V <sub>cc</sub>	−0.5 to +7.0	V
Terminal voltage <sup>*1</sup>	V <sub>T</sub>	$-0.5^{*2}$ to $V_{CC} + 0.3^{*3}$	V
Power dissipation	P <sub>T</sub>	1.0	W
Operating temperature	Topr	0 to + 70	°C
Storage temperature	Tstg	-55 to +125	°C
Storage temperature under bias	Tbias	-10 to +85	°C

Notes: 1. Relative to V<sub>ss</sub>

2.  $V_T$  min: -3.0 V for pulse half-width  $\leq 50$  ns

3. Maximum voltage is 7.0 V

# **Recommended DC Operating Conditions** (Ta = 0 to +70 °C)

Parameter	Symbol	Min	Тур	Max	Unit	
Supply voltage	$V_{cc}$	4.5	5.0	5.5	V	
	$V_{SS}$	0	0	0	V	
Input high (logic 1) voltage	$V_{IH}$	2.2	_	V <sub>cc</sub> +0.3	V	
Input low (logic 0) voltage	V <sub>IL</sub>	-0.5 <sup>*1</sup>	_	0.8	V	

Note: 1.  $V_{IL}$  min: -3.0 V for pulse half-width  $\leq 50$  ns

**DC Characteristics** (Ta = 0 to +70°C, 
$$V_{CC}$$
 = 5 V ±10%,  $V_{SS}$  = 0 V)

Parameter		Symbol	Min	Typ*1	Max	Unit	Test Conditions
Input leakage current		ILI	_	_	1	μΑ	$Vin = V_{SS}$ to $V_{CC}$
Output leakage current		I <sub>LO</sub>	_		1	μΑ	$\overline{\text{CS}} = \text{V}_{\text{IH}} \text{ or } \overline{\text{OE}} = \text{V}_{\text{IH}} \text{ or } \overline{\text{WE}} = \text{V}_{\text{IL}},$ $\text{V}_{\text{SS}} \leq \text{V}_{\text{I/O}} \leq \text{V}_{\text{CC}}$
Operating power supply current		I <sub>cc</sub>	_	6	15	mA	$\overline{CS} = V_{IL}$ others = $V_{IH}/V_{IL}$ $I_{I/O} = 0 \text{ mA}$
Average operating power supply current	HM62256B-4	I <sub>CC1</sub>		_	70	mA	min cycle, duty = 100 %, $I_{VO}$ = 0 mA $\overline{CS}$ = $V_{IL}$ , others = $V_{IH}/V_{IL}$
	HM62256B-5	I <sub>CC1</sub>	_	_	60		
	HM62256B-7	I <sub>CC1</sub>	_	33	60		
	HM62256B-8	I <sub>CC1</sub>	_	29	50		
		I <sub>CC2</sub>	_	5	15	mA	Cycle time = 1 $\mu$ s, $I_{I/O}$ = 0 mA $\overline{CS}$ = $V_{IL}$ , $V_{IH}$ = $V_{CC}$ , $V_{IL}$ = 0
Standby power supply current		I <sub>SB</sub>	_	0.3	2	mA	CS = V <sub>IH</sub>
		I <sub>SB1</sub>	_	0.2	100	μΑ	$Vin \ge 0 \text{ V}, \overline{CS} \ge V_{CC} - 0.2 \text{ V},$
			_	0.2*2	50 <sup>*2</sup>		
				0.2*3	10 <sup>*3</sup>		
Output low voltage		V <sub>OL</sub>	_	_	0.4	٧	I <sub>OL</sub> = 2.1 mA
Output high voltage		V <sub>OH</sub>	2.4	_	_	V	$I_{OH} = -1.0 \text{ mA}$

Notes: 1. Typical values are at  $V_{CC} = 5.0 \text{ V}$ ,  $Ta = +25^{\circ}\text{C}$  and not guaranteed.

- 2. This characteristics is guaranteed only for L-SL version.
- 3. This characteristics is guaranteed only for L-UL version.

# Capacitance (Ta = 25°C, f = 1.0 MHz)\*1

Parameter	Symbol	Min	Тур	Max	Unit	Test Conditions
Input capacitance <sup>*1</sup>	Cin	_	_	8	pF	Vin = 0 V
Input/output capacitance <sup>*1</sup>	C <sub>I/O</sub>	_	_	10	pF	V <sub>I/O</sub> = 0 V

Note: 1. This parameter is sampled and not 100% tested.

AC Characteristics (Ta = 0 to +70°C,  $V_{CC}$  = 5 V  $\pm$  10%, unless otherwise noted.)

#### **Test Conditions**

• Input pulse levels: 0.8 V to 2.4 V

• Input rise and fall times: 5 ns

• Input and output timing reference level: 1.5 V

• Output load: HM62256B-4: 1 TTL Gate + C<sub>L</sub> (30 pF)(Including scope & jig)

HM62256B-5: 1 TTL Gate +  $C_L$  (50 pF)(Including scope & jig) HM62256B-7/8: 1 TTL Gate +  $C_L$  (100 pF)(Including scope & jig)

#### Read Cycle

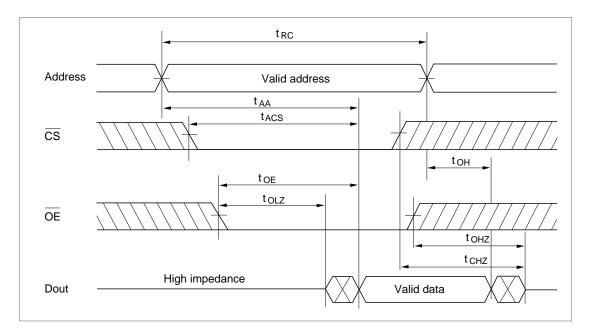
#### HM62256B

		-4		-5		-7		-8			
Parameter	Symbol	Min	Max	Min	Max	Min	Max	Min	Max	Unit	Notes
Read cycle time	t <sub>RC</sub>	45	_	55	_	70	_	85	_	ns	
Address access time	t <sub>AA</sub>	_	45	_	55	_	70	_	85	ns	
Chip select access time	t <sub>ACS</sub>	_	45	_	55	_	70	_	85	ns	
Output enable to output valid	t <sub>OE</sub>		30	_	35	_	40	_	45	ns	
Chip selection to output in low-Z	t <sub>CLZ</sub>	5	_	5	_	10	_	10	_	ns	2
Output enable to output in low-Z	t <sub>OLZ</sub>	5	_	5	_	5	_	5	_	ns	2
Chip deselection in to output in high-Z	t <sub>CHZ</sub>	0	20	0	20	0	25	0	30	ns	1, 2
Output disable to output in high-Z	t <sub>OHZ</sub>	0	20	0	20	0	25	0	30	ns	1, 2
Output hold from address change	t <sub>oh</sub>	5	_	5	_	5	_	10	_	ns	

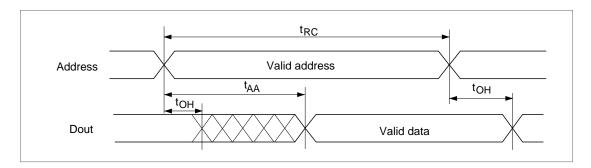
Notes: 1.  $t_{CHZ}$  and  $t_{OHZ}$  defined as the time at which the outputs achieve the open circuit conditions and are not referred to output voltage levels.

2. This parameter is sampled and not 100% tested.

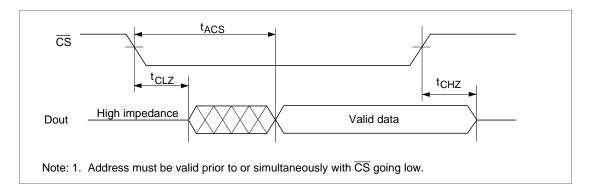
# Read Timing Waveform (1) $(\overline{WE} {=} V_{IH})$



# Read Timing Waveform (2) $(\overline{WE}{=}V_{IH},\overline{CS}{=}V_{IL},\overline{OE}{=}V_{IL})$



# Read Timing Waveform (3) $(\overline{WE}=V_{IH}, \overline{OE}=V_{IL})^{*1}$



#### Write Cycle

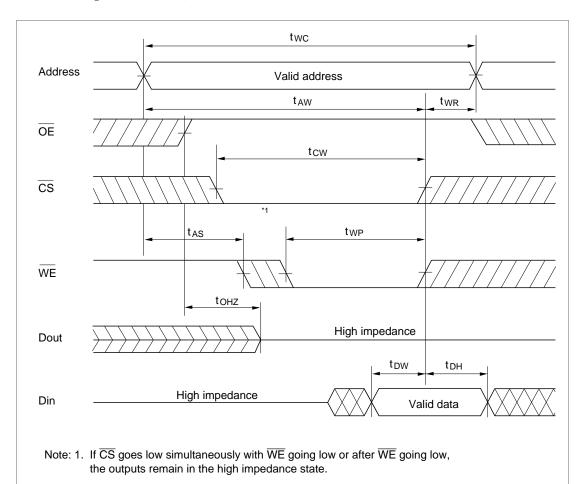
HM62256E	Н	М	62	25	6	В
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		-4		-5		-7		-8			
Parameter	Symbol	Min	Max	Min	Max	Min	Max	Min	Max	Unit	Notes
Write cycle time	t <sub>wc</sub>	45	_	55	_	70	_	85	_	ns	
Chip selection to end of write	t <sub>cw</sub>	35	_	40	_	60	_	75	_	ns	4
Address setup time	t <sub>AS</sub>	0	_	0	_	0	_	0	_	ns	5
Address valid to end of write	t <sub>AW</sub>	35	_	40	_	60	_	75	_	ns	
Write pulse width	t <sub>wP</sub>	30	_	35	_	50	_	55	_	ns	3, 8
Write recovery time	t <sub>wR</sub>	0	_	0	_	0	_	0	_	ns	6
WE to output in high-Z	t <sub>whz</sub>	0	20	0	20	0	25	0	40	ns	1, 2, 7
Data to write time overlap	t <sub>DW</sub>	20	_	25	_	30	_	35	_	ns	-
Data hold from write time	t <sub>DH</sub>	0	_	0	_	0	_	0	_	ns	
Output active from end of write	t <sub>ow</sub>	5	_	5	_	5	_	5	_	ns	2
Output disable to output in high-Z	t <sub>OHZ</sub>	0	20	0	20	0	25	0	40	ns	1, 2, 7

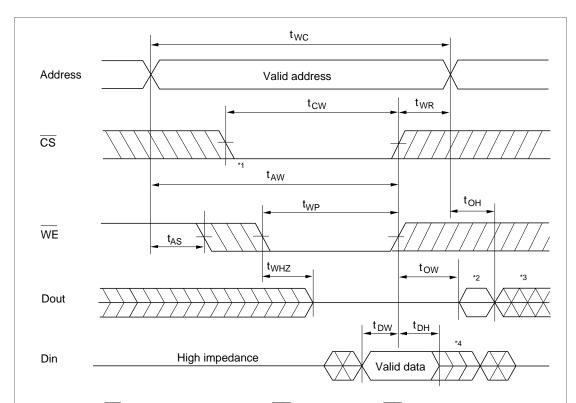
Notes: 1. t<sub>OHZ</sub> and t<sub>WHZ</sub> are defined as the time at which the outputs achieve the open circuit conditions and are not referred to output voltage levels.

- 2. This parameter is sampled and not 100% tested.
- 3. A write occurs during the overlap  $(t_{WP})$  of a low  $\overline{CS}$  and a low  $\overline{WE}$ . A write begins at the later transition of  $\overline{CS}$  going low or  $\overline{WE}$  going low. A write ends at the earlier transition of  $\overline{CS}$  going high or  $\overline{WE}$  going high.  $t_{WP}$  is measured from the beginning of write to the end of write.
- 4.  $t_{\text{cw}}$  is measured from  $\overline{\text{CS}}$  going low to the end of write.
- 5.  $t_{\rm AS}$  is measured from the address valid to the beginning of write.
- 6.  $t_{wR}$  is measured from the earlier of  $\overline{WE}$  or  $\overline{CS}$  going high to the end of write cycle.
- 7. During this period, I/O pins are in the output state so that the input signals of the opposite phase to the outputs must not be applied.
- In the write cycle with OE low fixed, t<sub>WP</sub> must satisfy the following equation to avoid a problem of data bus contention, t<sub>WP</sub> ≥ t<sub>WHZ</sub> max + t<sub>DW</sub> min.

### Write Timing Waveform (1) (OE Clock)



Write Timing Waveform (2) ( $\overline{OE}$  Low Fixed) ( $\overline{OE} = V_{IL}$ )



Notes: 1. If  $\overline{\text{CS}}$  goes low simultaneously with  $\overline{\text{WE}}$  going low or after  $\overline{\text{WE}}$  going low, the outputs remain in the high impedance state.

- 2. Dout is the same phase of the write data of this write cycle.
- 3. Dout is the read data of next address.
- 4. If  $\overline{\text{CS}}$  is low during this period, I/O pins are in the output state. Therefore, the input signals of the opposite phase to the output must not be applied to them.

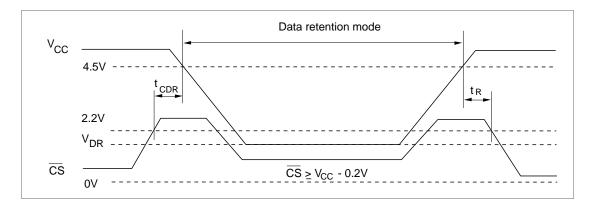
Low  $V_{CC}$  Data Retention Characteristics (Ta = 0 to +70°C)

Parameter	Symbol	Min	Typ*1	Max	Unit	Test Conditions <sup>*6</sup>
V <sub>cc</sub> for data retention	$V_{DR}$	2.0	_	5.5	V	$\overline{\text{CS}} \ge \text{V}_{\text{CC}} - 0.2 \text{ V},$ $\text{Vin } \ge 0 \text{ V}$
Data retention current	I <sub>CCDR</sub>	_	0.05	30 <sup>*2</sup>	μΑ	V <sub>CC</sub> = 3.0 V, Vin ≥ 0 V
		_	0.05	10 <sup>*3</sup>		$\overline{\text{CS}} \ge V_{\text{CC}} - 0.2 \text{ V},$
		_	0.05	3*4		
Chip deselect to data retention time	t <sub>CDR</sub>	0	_	_	ns	See retention waveform
Operation recovery time	t <sub>R</sub>	t <sub>RC</sub> *5	_	_	ns	

Notes: 1. Typical values are at  $V_{cc} = 3.0 \text{ V}$ ,  $Ta = 25^{\circ}\text{C}$  and not guaranteed.

- 2.  $10 \mu A \text{ max at Ta} = 0 \text{ to} + 40^{\circ} \text{C}.$
- 3. This characteristics guaranteed for only L-SL version. 3  $\mu$ A max at Ta = 0 to +40°C.
- 4. This characteristics guaranteed for only L-UL version.  $0.6 \,\mu\text{A}$  max at Ta = 0 to +40°C.
- 5.  $t_{RC}$  = read cycle time.
- 6.  $\overline{\text{CS}}$  controls address buffer,  $\overline{\text{WE}}$  buffer,  $\overline{\text{OE}}$  buffer, and Din buffer. If  $\overline{\text{CS}}$  controls data retention mode, other input levels (address,  $\overline{\text{WE}}$ ,  $\overline{\text{OE}}$ , I/O) can be in the high impedance state.

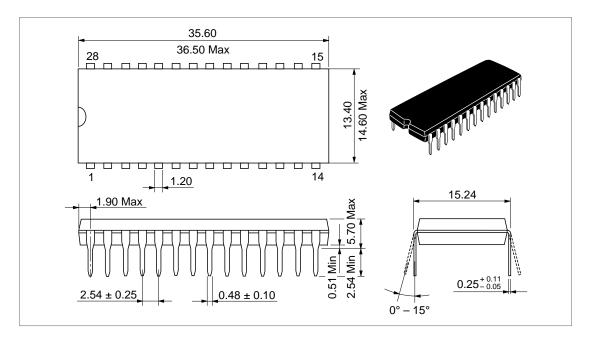
#### Low $\boldsymbol{V}_{CC}$ Data Retention Timing Waveform



# **Package Dimensions**

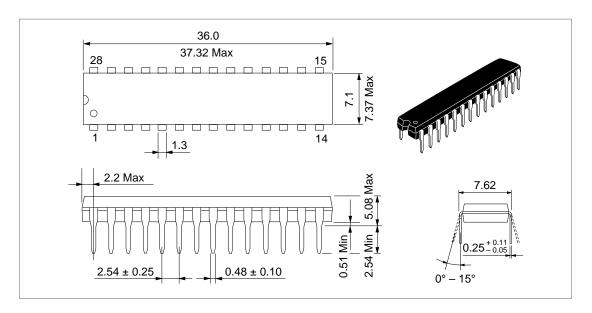
#### HM62256BLP Series (DP-28)

Unit: mm



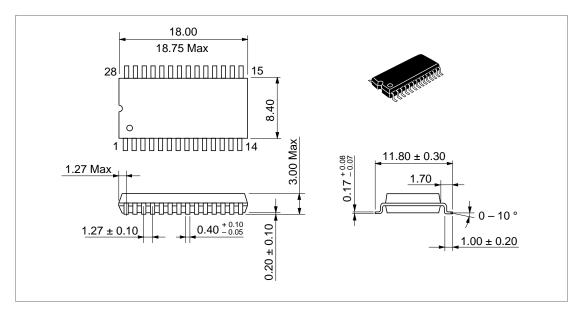
### HM62256BLSP Series (DP-28NA)

Unit: mm



#### HM62256BLFP Series (FP-28DA)

Unit: mm



### HM62256BLT Series (TFP-32DA)

Unit: mm

